

Industrial Keynote

Accurate Materials' Testing as an Enabler for Microwave and Millimeter-Wave Industries

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Outline:

1. Introduction to IMS SC-31 (Th1E, Th2E).
2. Microwaves and Materials.
3. Material Data for Microwave Engineering.
4. QWED's Position on the Scene.
5. Industrial Benchmarking Initiatives – iNEMI.
6. Summary and Outlook.

Emerging Technologies

- 28 **AI/ML for RF to mmWave** – AI/ML, algorithms implementations, and demonstrations for: spectrum sensing; mobile edge networking; MIMO and array beam operations and management; design and optimization; in-situ sensing, diagnostics, control, reconfiguration of MHz to THz communication and sensing circuits and systems
- 29 **Quantum devices, circuits, and systems** – Quantum devices and circuits (incl. cryogenic RF circuits); algorithms, interfaces, and systems for quantum computing and quantum sensing applications
- 30 **SubTHz and THz circuits and systems** – SubTHz and THz systems (300GHz to 1 THz+), incl. sub-THz architectures and implementations for passive and active sensing, 6G and Future-G communication systems.
- 31 **Microwave field-matter interaction, material sensing and high-power applications** – Industrial and scientific applications of microwave energy (e.g., chemistry, metallurgy, ceramic sintering, plasma generation, waste treatment, “green” materials, energy converters); MHz-to-THz sensing (from microwave microscopy to large surface/volume imaging) of materials for electronics and energy applications; multiphysics modeling of materials processing and characterization.
- 32 **Other innovative MHz-to-THz systems and applications** – Submissions that describe innovative contributions in new and emerging areas of interest to the MTT community not falling under the above categories are encouraged.

Th1E: Material Sensing at Microwave and mm-Wave Frequencies

Chair: Zoya Popović

Chair organization: University of Colorado Boulder

Co-chair: Pawel Kopyt

Co-chair organization: Warsaw Univ. of Technology

Location: 146C

Abstract:

Advances in material sensing and characterization techniques from S to W frequency bands are presented. Instruments based on resonators, planar transmission lines, and free-space radar are discussed.

Th2E: Near-Field Wave-Matter Interaction

Chair: Kamel Haddadi

Chair organization: Université de Lille

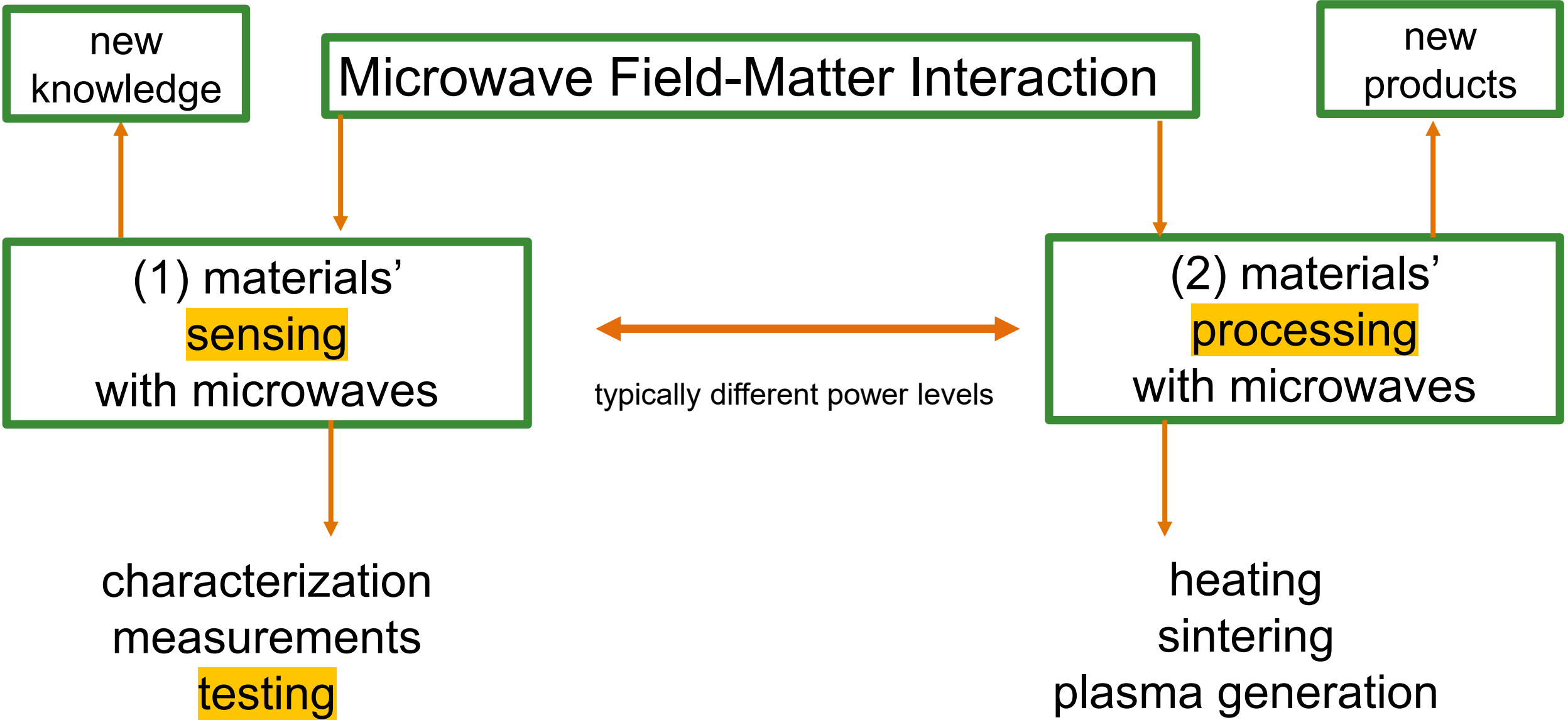
Co-chair: Malgorzata Celuch

Co-chair organization: QWED

Location: 146C

Abstract:

This session covers wave-material interactions ranging from microwave microscopy to high-power-density plasma generation. Near-field microscopy for high-resolution material characterization at room and cryogenic temperatures is shown using frequencies from 2 to 12GHz. Additionally, resonator-based field enhancement is shown for low-power plasma generation in the 2.45GHz ISM band.



Introduction to IMS SC-31: Topic (2)

2009 International Microwave Symposium

7-12 June, Boston Convention & Exhibition Center
IEEE Microwave Theory and Techniques Society

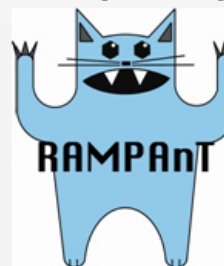


Recent Advances in Microwave Power Applications and Techniques IMS 2009 Workshop: 12 June 2009, Friday, full day

Come and stay

RAMPAnT

for new concepts and markets
in microwave theory and techniques!



IMPI/MTT-S WORKSHOP ON
INDUSTRIAL APPLICATIONS OF MICROWAVES
IEEE MTT-S International Microwave Symposium
San Francisco, CA, May 29, 1981

List of Speakers

1. H.F. Huang (DuPont) –
Industrial and Consumer Applications of Microwaves and the Role of the International Microwave Power Institute (IMPI)
 2. F. Hammersand and E. Adams (RCA) –
Care and Operation of High Power Magnetrons for Industrial Applications
 3. I. Namba and H. Sitao (Toshiba) –
The Design and Application of Magnetrons in Microwave Ovens
 4. K.L. Carr (M/A – COM) –
Ferrite Circulators for Microwave Ovens
- (LUNCHEON BREAK)
5. M.T. Long (American Microwave Technology) –
Low-Cost Microwave Power Transistors for Microwave Ovens
 6. J.P. Quine (General Electric) –
Microwave Impedance and Heating Characteristics of Microwave Ovens
 7. J.M. Osepchuk (Raytheon) –
Safety and RFI Considerations in Microwave Power Applications.
 8. Panel Discussion (All Speakers)

IEEE MTT-S 2023 IMS Workshop WMG: Recent Advances in Industrial Microwave Power Applications

Organizers:

Zoya Popović, University of Colorado Boulder, CO, USA
Vadim V. Yakovlev, Worcester Polytechnic Institute, MA, USA
Małgorzata Celuch, QWED, Warsaw, Poland



International Microwave Symposium
11-16 June 2023, San Diego, CA



<https://impi.org/>



<https://www.ampereurope.org/>



2009 IEEE MTT-S International Microwave Symposium

Highest Quality Workshop

This award is hereby presented to:

Małgorzata Celuch

For organizing the workshop

“Recent Advances in Microwave Power Applications and Techniques (RAMPAnT)”

Boston, Massachusetts

Friday, June 12, 2009


 Fred Schindler
 IMS2009 General Chair


 Lawrence Kushner
 IMS2009 Technical Program Co-Chair


 Greg Lyons
 IMS2009 Workshop Chair

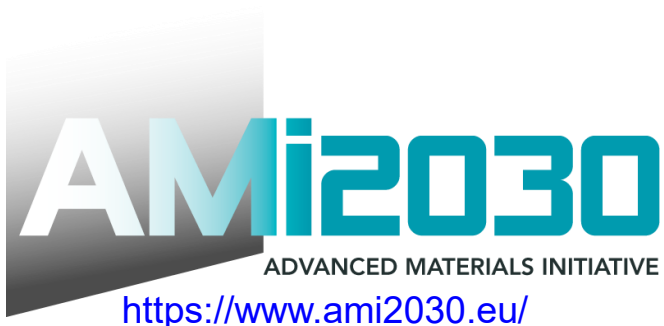

 Mark Gouker
 IMS2009 Technical Program Co-Chair

IMS papers related to materials **testing / sensing** with microwaves are:

- not so many
- dispersed among different sessions

SC-31 aims to:

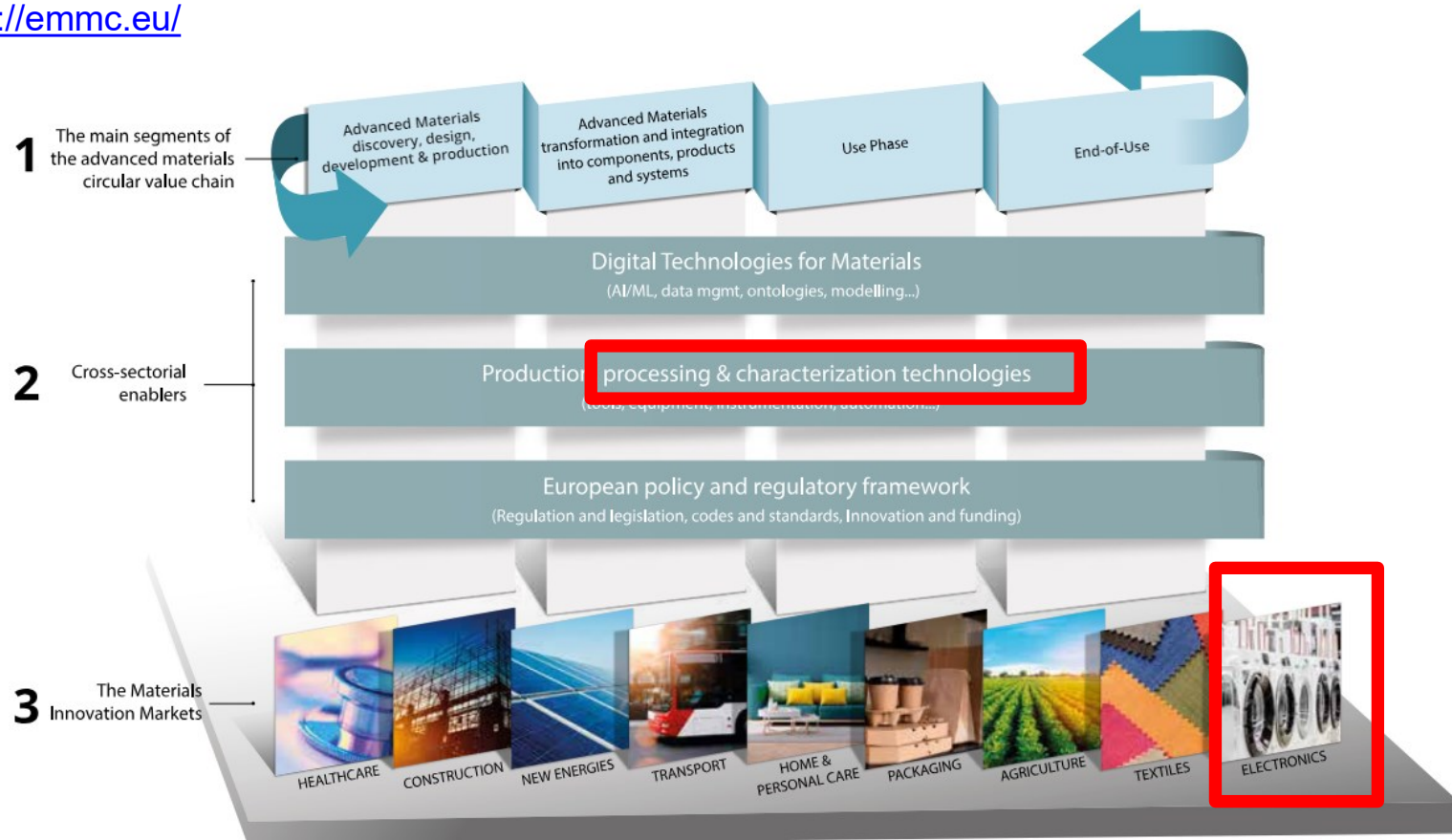
- + attract more papers
- + define coherent facilitating vivid discussions



<https://emmc.eu/>



STRATEGIC MATERIALS AGENDA

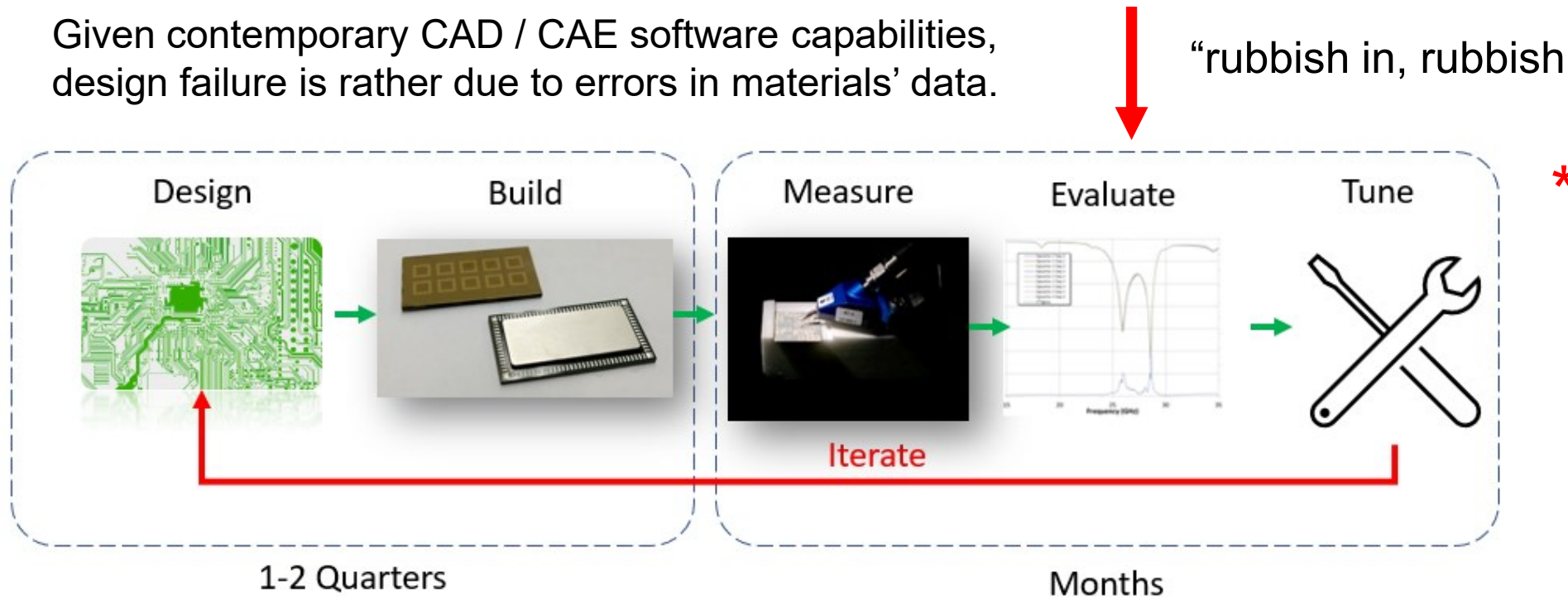


Materials come into play once you build a circuit.

CAD / CAE software can take nearly anything in.

Given contemporary CAD / CAE software capabilities, design failure is rather due to errors in materials' data.

“rubbish in, rubbish out”



Errors may cost \$10's of millions for a single program, or worse, unexpected product failures*

* figure and statement from https://www.inemi.org/article_content.asp?adminkey=5cc4f4100ebf2ba1f3e6fd6294749139&article=161

participates to projects evaluating:

dielectric losses

conductor losses



- fast & precise **measurement** methods,
- physical insight with computer **modelling**,
- **dissemination** (in IEEE and EU communities).

5G/mmWave

- [5G/mmWave Materials Assessment and Characterization](#)

5G/mmWave

- [mmWave Permittivity Reference Material Development](#)
- Also see Roadmap: [5G/6G mmWave Materials and Electrical Test Technology Roadmap \(5G/6G MAESTRO\)](#)

Board Assembly

- [Bi-Sn Based Low-Temperature Soldering Process and Reliability](#)
- [Characterization of Third Generation High-Reliability Pb-Free Alloys](#)
- [Conformal Coating Evaluation for Environmental Protection against Corrosive Environments, Phase 3](#)
- [Connector Reliability Test Recommendations, Phase 3](#)
- [Electromigration of SiBn Solder for Second-Level Interconnect](#)
- [QFN Package Board Level Reliability](#)

Optoelectronics

- [Best Practices for Expanded Beam Connectors in Data Centers](#)

Packaging

- [Impact of Low CTE Mold Compound on Second-Level Board Reliability, Phase 2](#)
- [Low Temperature Material Discovery and Characterization for First Level Interconnect](#)
- [Moisture Induced Expansion Metrology for Packaging Polymetric Materials Project, Phase 1](#)
- [PLP Fine Pitch Substrate Inspection/Metrology, Phase 4](#)
- [RDL Adhesion Strength Measurement Project](#)
- [Warpage Characterization and Management Program](#)
 - [High Density Interconnect Socket Warpage Prediction and Characterization](#)

PCB & Laminates

- [Reliability & Loss Properties of Copper Foils for 5G Applications](#)
- [PCBA Materials for Harsh Environments, Phase 2](#)
- [Hybrid PCBs for Next Generation Applications](#)
- [PCB Characterization for CAF and ECM Failure Mitigation](#)
- [PCB Connector Footprint Tolerance](#)

Wojciech Gwarek (2001)
*“theory and applications
of electromagnetic modeling”*



Jerzy Krupka (2012)
*“high frequency measurements
of electromagnetic properties of materials”*

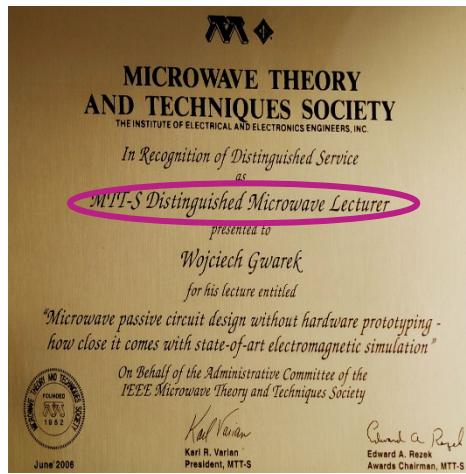
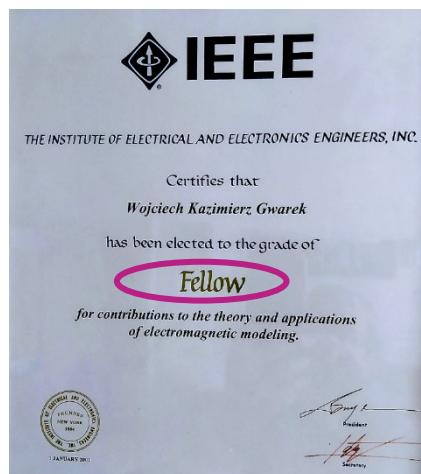


QWED origins in Computational Electromagnetics

since 1980s...

IEEE- awarded research of **Wojciech Gwarek**

Fellow, Pioneer Award, DML



- + conformal modeling of geometry
- + time-domain approach

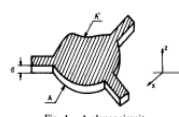
1997 first commercial licences sold by QWED

... by early 2000s, QuickWave-3D by QWED used worldwide for industrial & research applications from RF to optical bands

IEEE TRANSACTIONS ON MICROWAVE THEORY AND TECHNIQUES, VOL. MTT-33, NO. 10, OCTOBER 1985 1067

Analysis of an Arbitrarily-Shaped Planar Circuit—A Time-Domain Approach

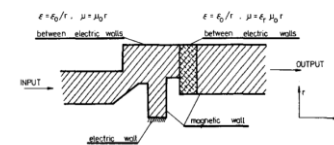
WOJCIECH K. GWAREK $\nabla V(x, y, t) = -L_s \frac{\partial J(x, y, t)}{\partial t}$
(Invited Paper) $\nabla \cdot J(x, y, t) = -C_s \frac{\partial V(x, y, t)}{\partial t}$



IEEE TRANSACTIONS ON MICROWAVE THEORY AND TECHNIQUES, VOL. 36, NO. 2, FEBRUARY 1988

Computer-Aided Analysis of Arbitrarily Shaped Coaxial Discontinuities

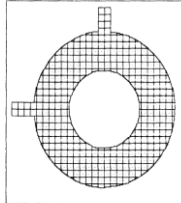
WOJCIECH K. GWAREK



IEEE TRANSACTIONS ON MICROWAVE THEORY AND TECHNIQUES, VOL. 36, NO. 4, APRIL 1988

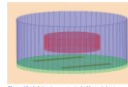
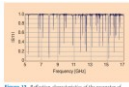
Analysis of Arbitrarily Shaped Two-Dimensional Microwave Circuits by Finite-Difference Time-Domain Method

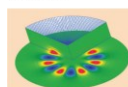
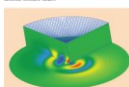
WOJCIECH K. GWAREK

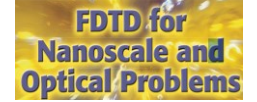


Industrial Design of Axisymmetrical Devices Using a Customized FDTD Solver from RF to Optical Frequency Bands

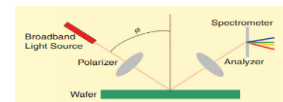
■ Malgorzata Celuch and Wojciech K. Gwarek







Bartłomiej Salski, Malgorzata Celuch, and Wojciech Gwarek

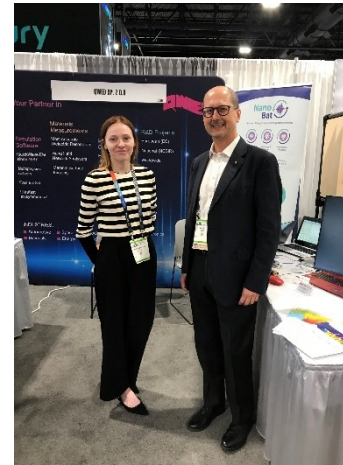




Anaheim, CA, 1999



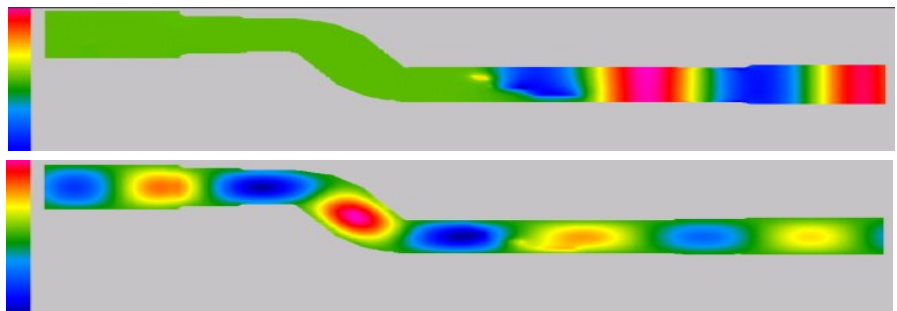
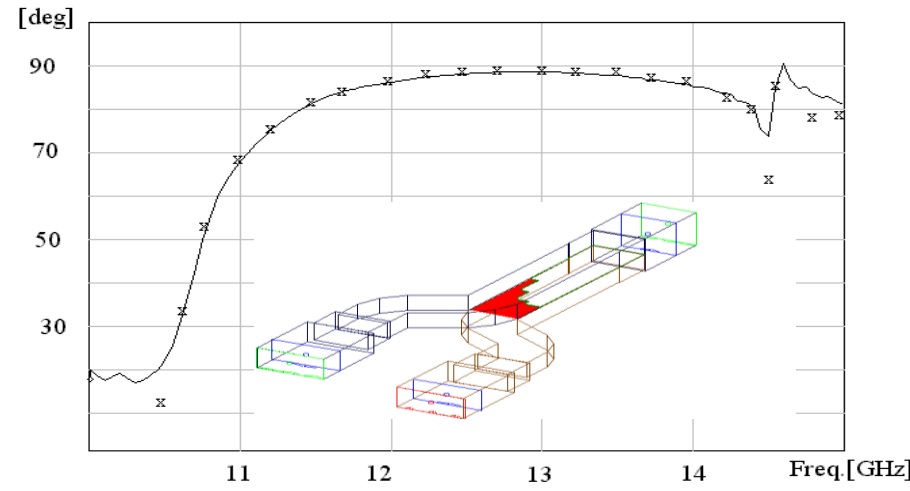
San Francisco, CA,
2006



Denver, 2022

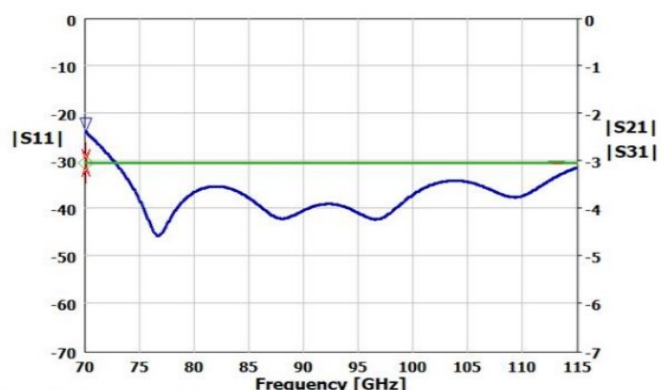
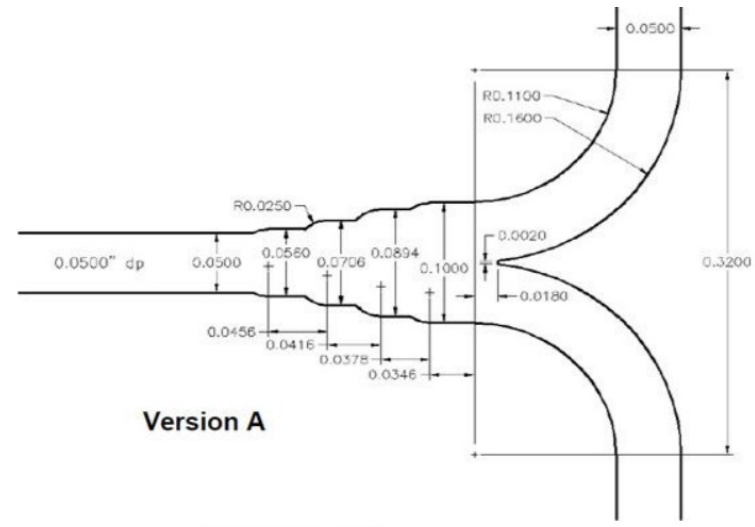
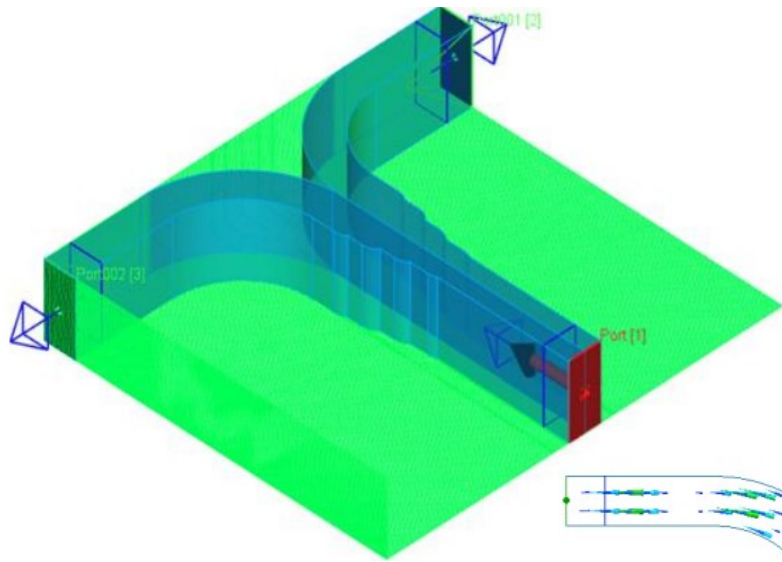


Septum polariser by SES
design & measurements: Saab Ericsson Space
modelling: QWED, 1997
 below: differential phase-shift

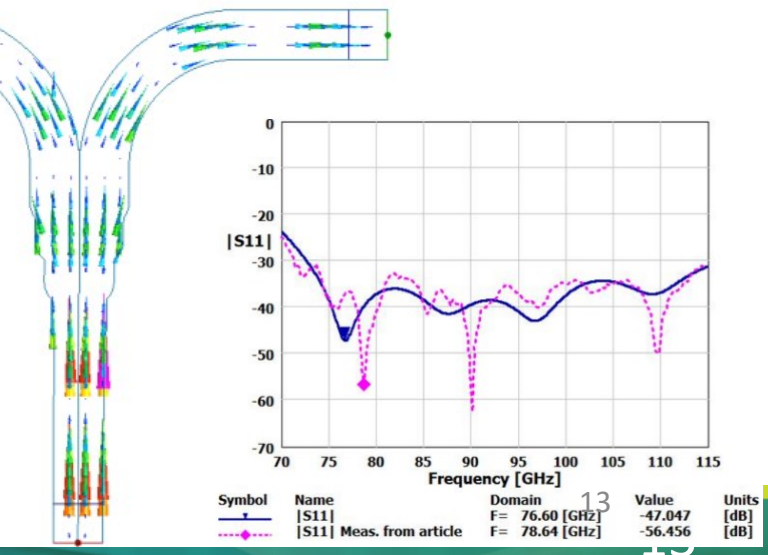


propagation of two polarisations
at centre frequency

E-plane Y-junction by NRAO
after A. R. Kerr, Elements for E-Plane Split-Block Waveguide
Circuits, ALMA Memo 381



| Symbol | Name | Domain | Value | Units |
|--------|------|----------------|---------|-------|
| — | S11 | F= 70.00 [GHz] | -23.587 | [dB] |
| — | S21 | F= 70.00 [GHz] | -3.011 | [dB] |
| — | S31 | F= 70.00 [GHz] | -3.012 | [dB] |

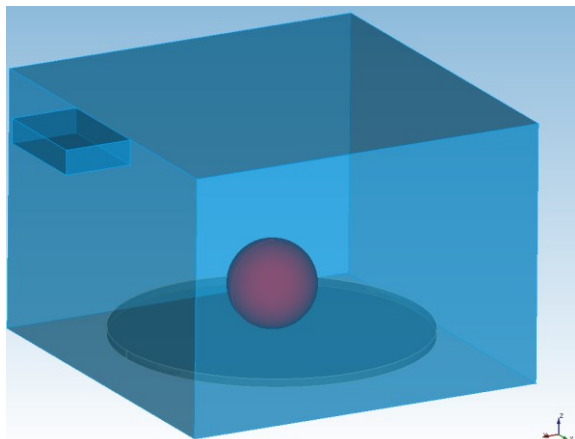


| Symbol | Name | Domain | Value | Units |
|--------|-------------------------|----------------|---------|-------|
| — | S11 | F= 76.60 [GHz] | -47.047 | [dB] |
| — | S11 Meas. from article | F= 78.64 [GHz] | -56.456 | [dB] |

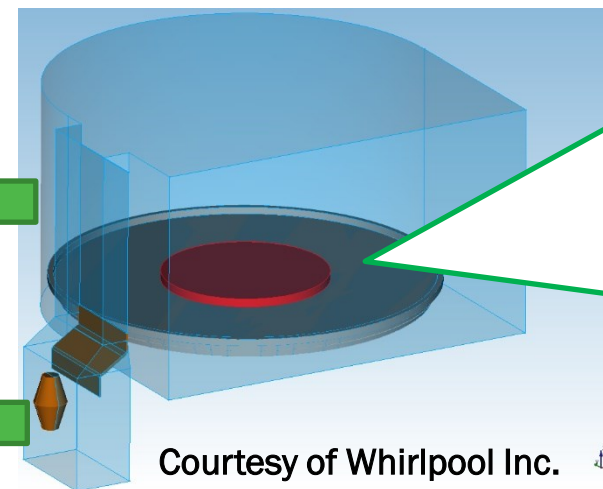
Applications for Materials Processing with Microwaves

Simple microwave heating benchmarks & microwave heating phenomena studies*

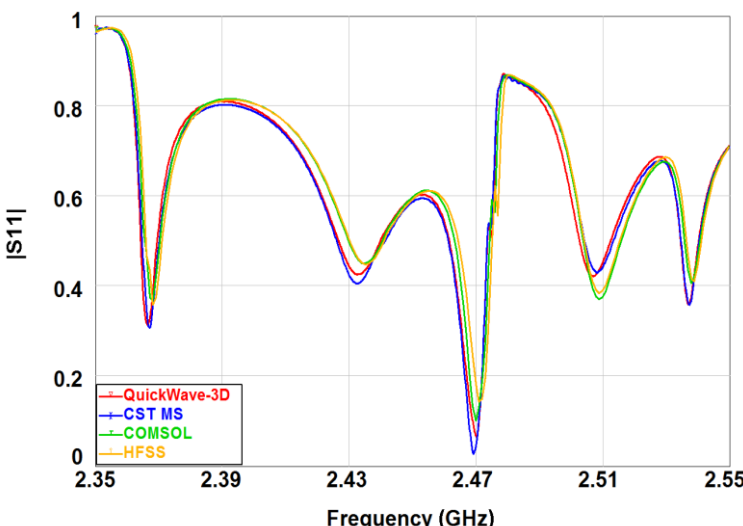
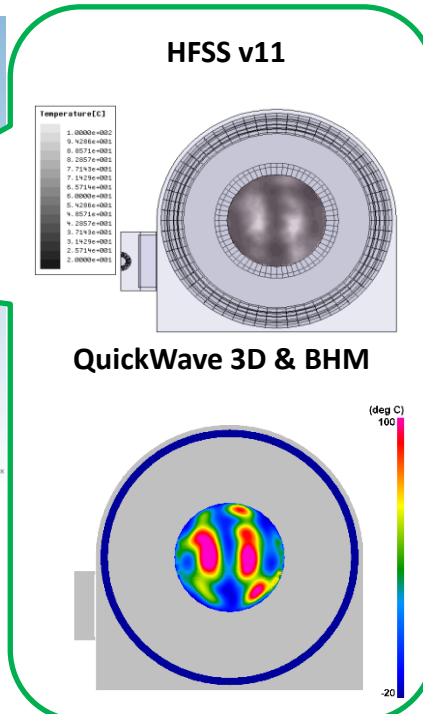
Design & analysis of real-life microwave oven cavities, incl. complicated cavity shapes and advanced feeding system*



- heat transfer & load dynamics
- Load rotation & arbitrary movement during heating
- Source parameters tuning – regime for solid state sources
- Temperature dependence of material parameters

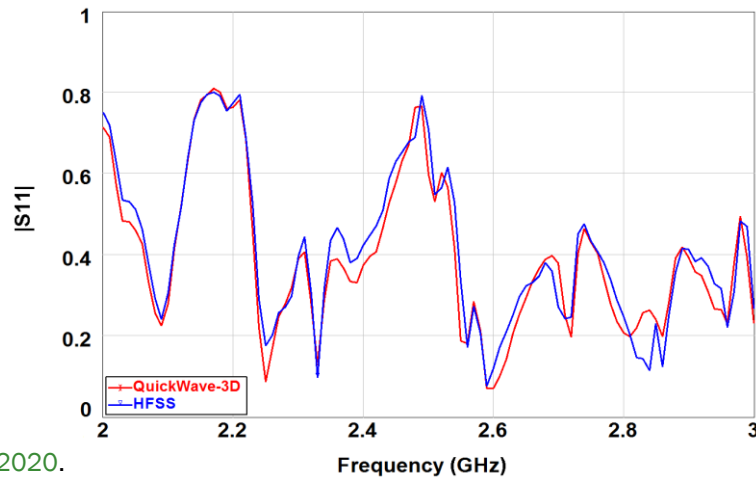


Courtesy of Whirlpool Inc. – Whirlpool MAX oven



Freezing to file the state of the simulation

De-freezing on arbitrary computer & at convenient time

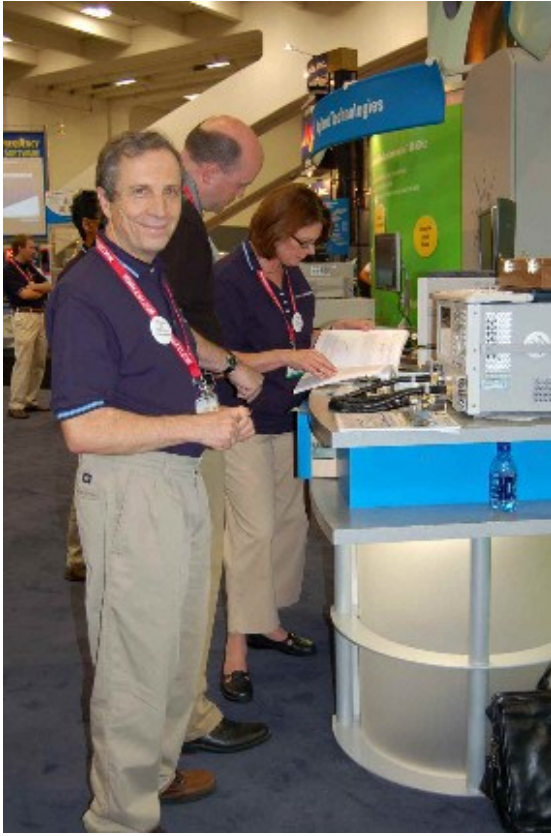
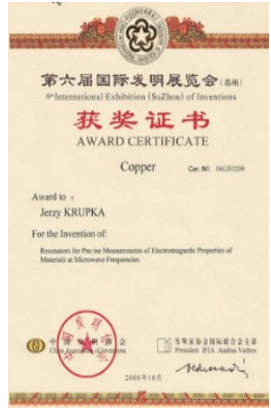
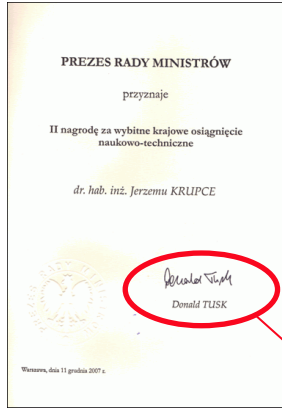
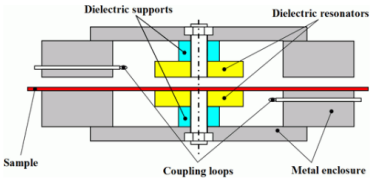


* M.Celuch, P.Kopyt & M. Olszewska-Placha in eds. M. Lorence, P. S. Pesheck, U. Erle, *Development of packaging and products for use in microwave ovens*, 2nd Ed. Elsevier 2020.

With QuickWave EM computation as fast as **1 min 18s** on a **low-cost video card** – supporting **all graphic cards with OpenCL**

since 1980s...

awarded research of **Jerzy Krupka** (IEEE Fellow) on dielectric resonators (best known: Split-Post Dielectric Resonator)

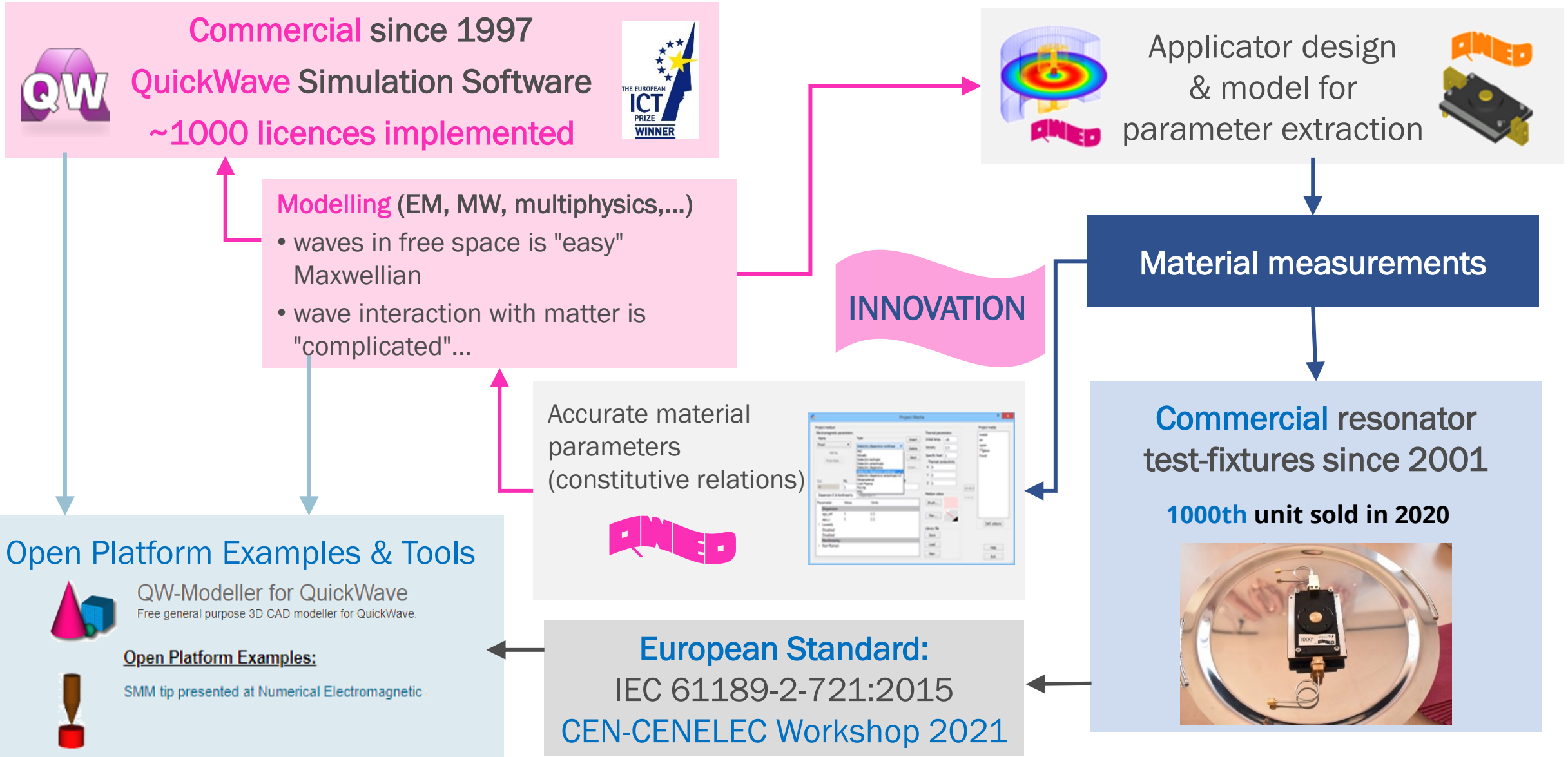


by Donald Tusk
Prime Minister of Poland 2007-2014
President of the European Council 2014-2019

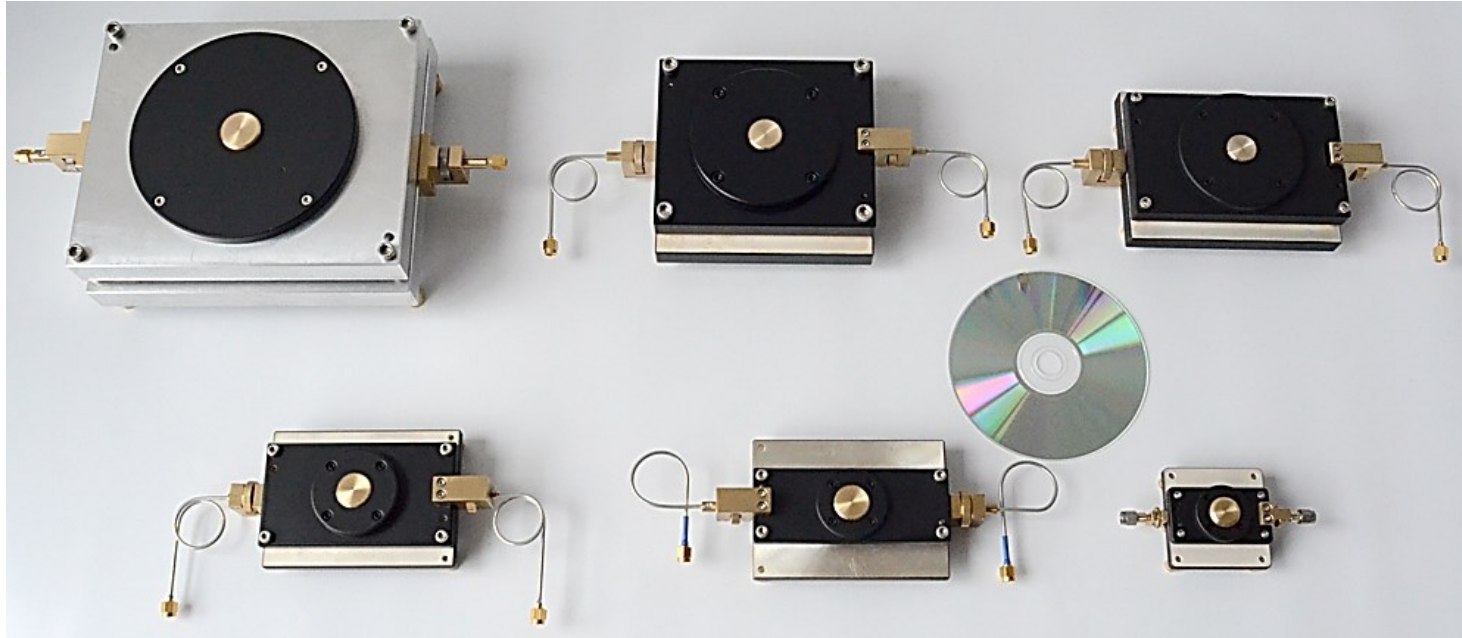
Agilent Both
IEEE IMS 2006,
San Francisco, CA

MMA-2010, Warsaw PL
co-organised by
QWED & Warsaw Univ.Tech.

Bridging Computer Modelling with Material Measurements



SPDRs for laminar dielectric materials
typical units: 1.1 GHz -15 GHz



T. Karpisz, B. Salski, P. Kopyt, and J. Krupka,
doi: 10.1109/TMTT.2019.2905549.

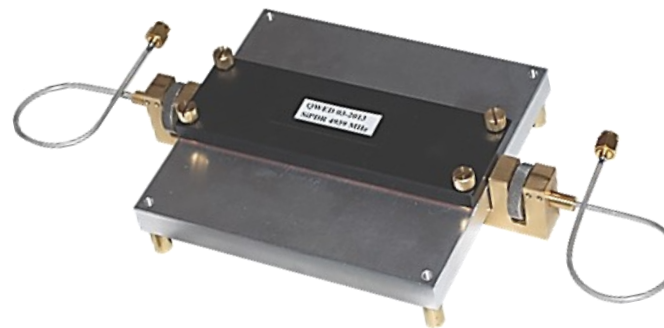
FPOR
20 -120
GHz



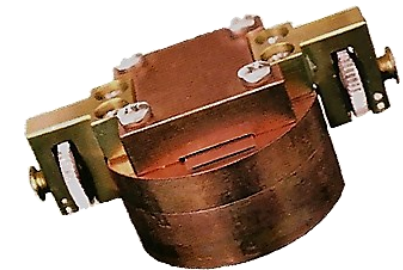
TE_{01δ} cavities, typically 1 – 10 GHz
for bulk low-loss dielectrics



5 GHz SiPDR for resistive sheets

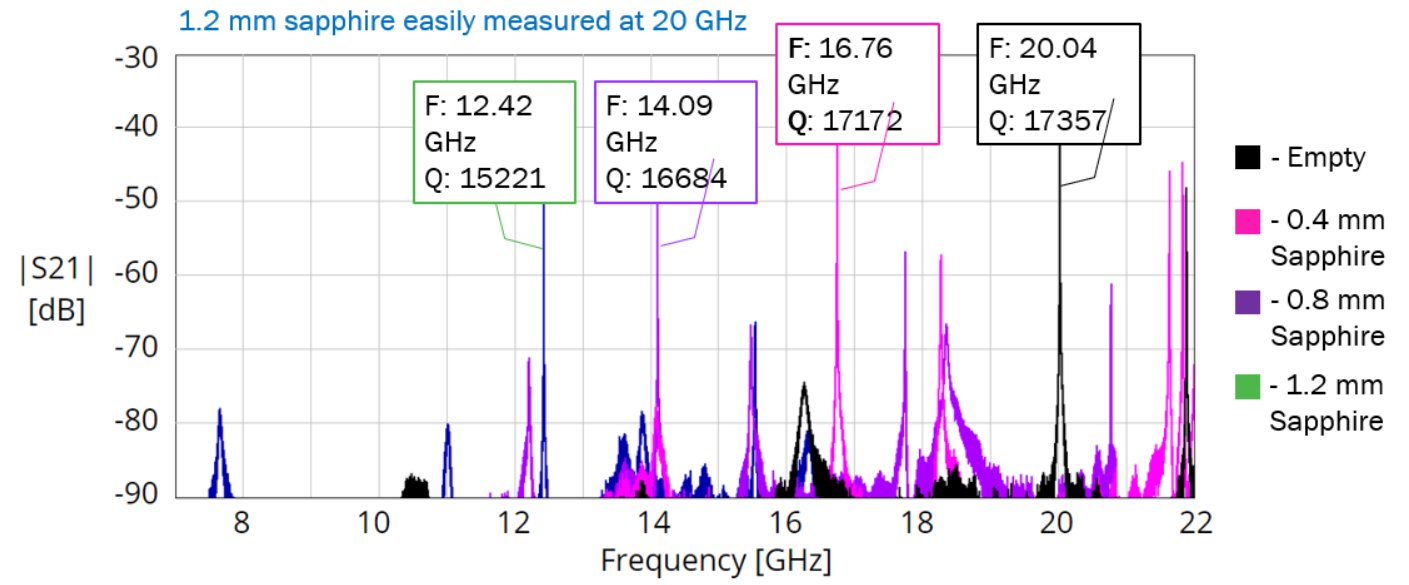
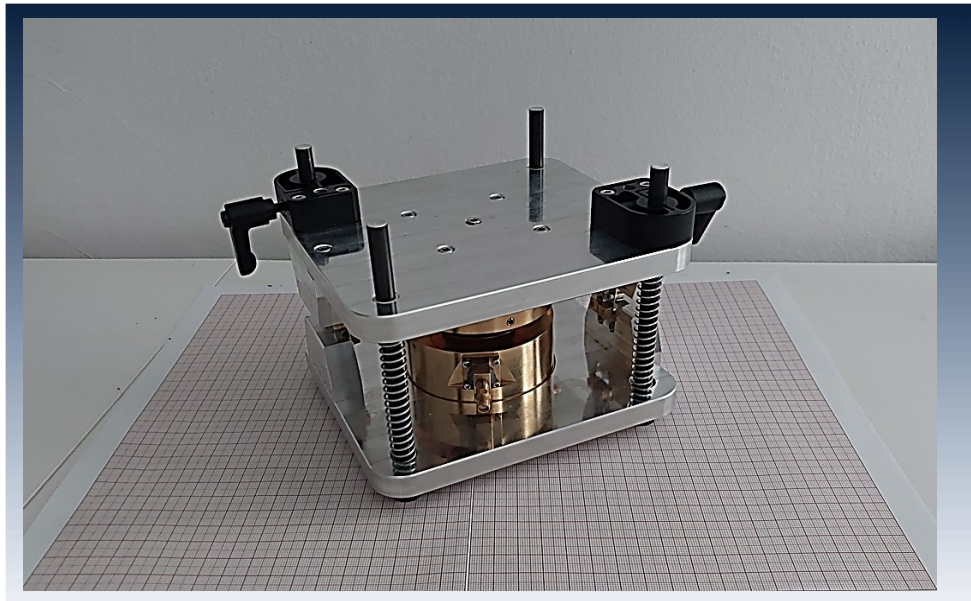
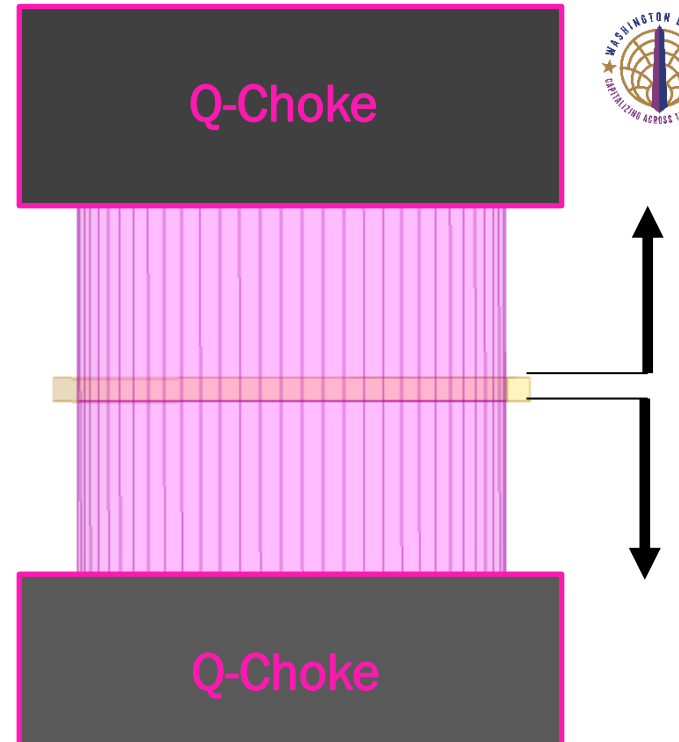


modified SiPDR for graphene





European patent application:
EP23461651 (Sep.2023)



No standards & SRMs for mmWave Permittivity measurements >20 GHz:

- Challenges for ISO and quality control

Few vendors for mmWave Permittivity measurement equipment >10 GHz:

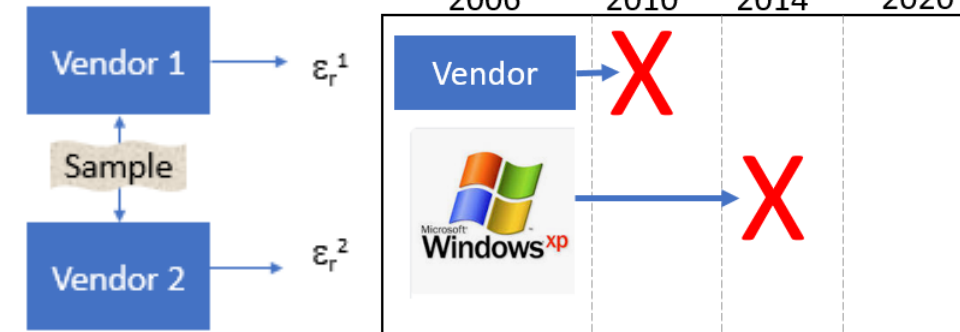
- Explain **vendor to vendor differences**
- Whom to trust?
- On whom to rely?

Useful 5G materials are typically **very low loss**:

- **Eliminates** many traditional transmission line techniques

Increasing frequency:

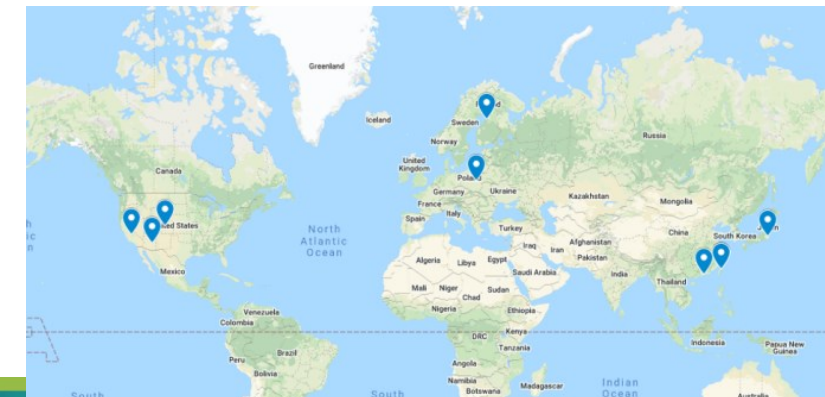
- **Incompatible** sample dimension requirements between techniques
- Higher **sensitivity to operator**



Our project:



- | | | |
|--|---|---|
| <ul style="list-style-type: none"> • 3M • AGC-Nelco • Ajinomoto USA • AT&S • Centro Ricerche FIAT-FCA • Dell • Dupont • EMD Electronics (Co-Chair) • Flex | <ul style="list-style-type: none"> • Georgia Tech • Showa Denko Materials • IBIDEN Co Ltd • IBM • Intel • Isola • ITRI (Co-Chair) • Keysight (Co-Chair) • MacDermid-Alpha | <ul style="list-style-type: none"> • Mosaic Microsystems • NIST • Nokia • Panasonic • QWED • Shengyi Technology Company • Sheldahl • Unimicron Technology Corp • Zestron |
|--|---|---|



First Round-Robin

Sample Material Requirements

- Stable, Low loss
- Low moisture absorption / temperature dependency
- Isotropic
- Good mechanical & handling properties

1st Project Stage

- Precision Teflon
- Cyclo Olefin Polymer

2nd Project Stage

- Rexolite
- Fused Silica

Industrial

- Automotive

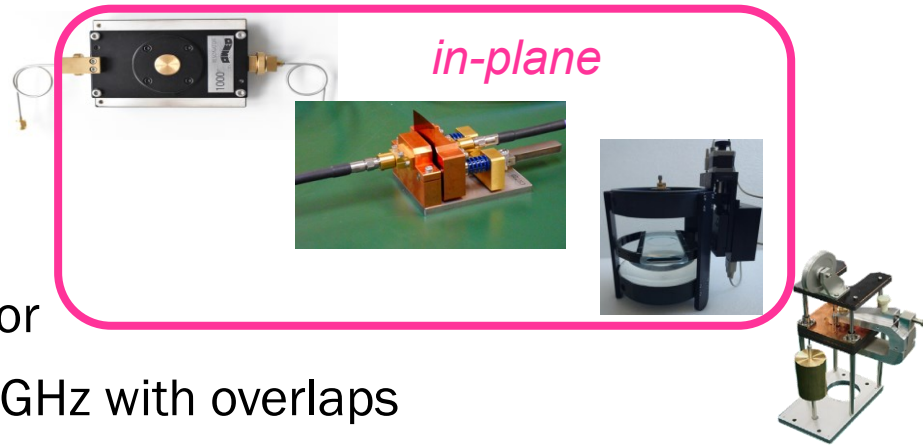
Techniques Included

- Split Post Dielectric Resonator
- Split Cavity Resonator
- Fabry-Perot
- Balanced Circular Disk Resonator

→ Frequency Span : 10GHz – 100GHz with overlaps

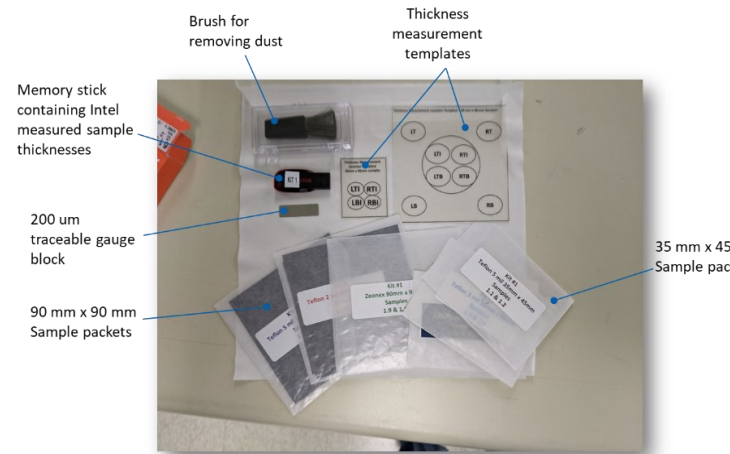
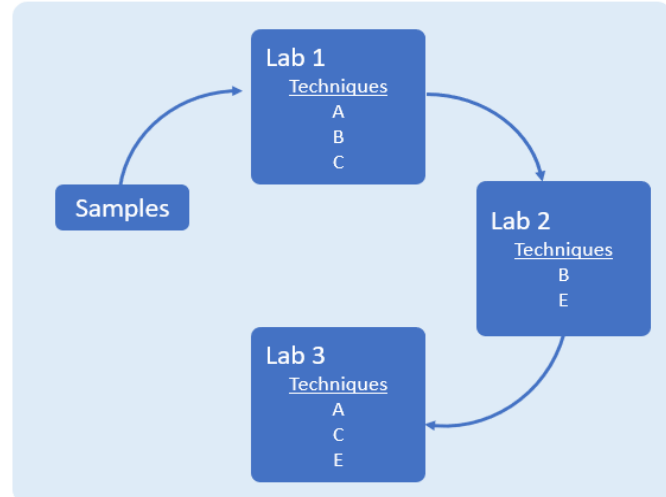
10 Sample Kits Created

- Sample sizes 35 mm x 45 mm, 90 mm x 90 mm



BCDR out-of-plane

10 Laboratory Round Robin



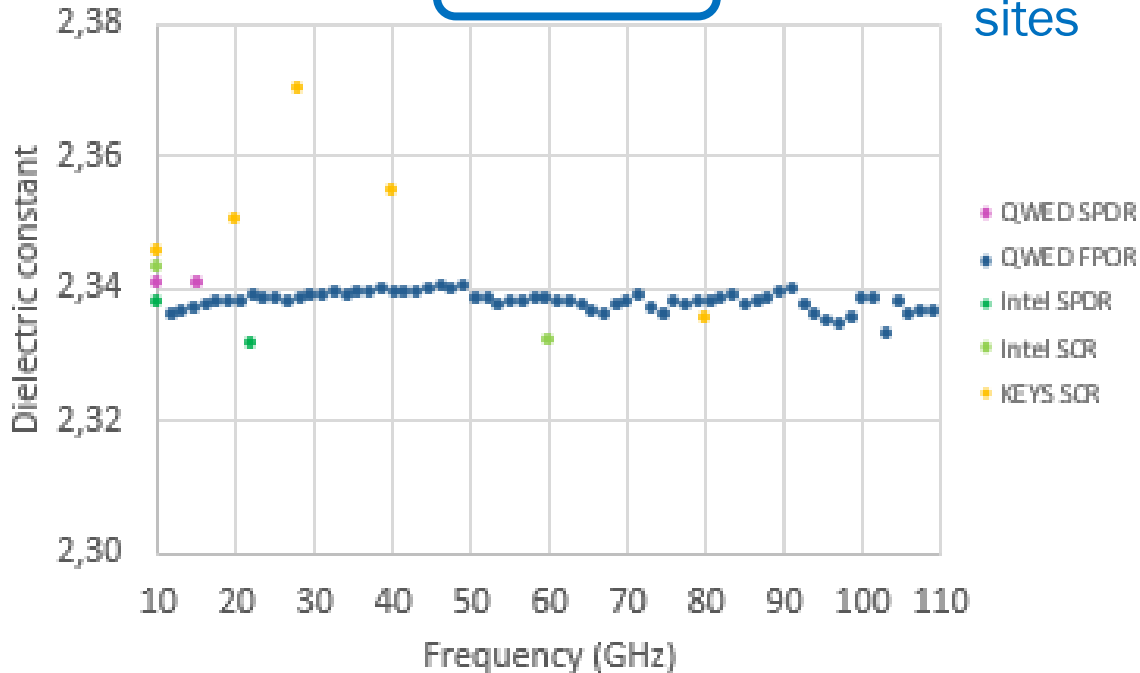
Resonators:

Intel - SCR at 10 / 60 GHz and SPDR at 10/ 20 GHz
 Keysight - SCR at 10 / 20 / 28 / 40 / 80 GHz
 QWED - SPDR at 10/ 15 GHz and FPOR 10-110GHz

VNA, software:

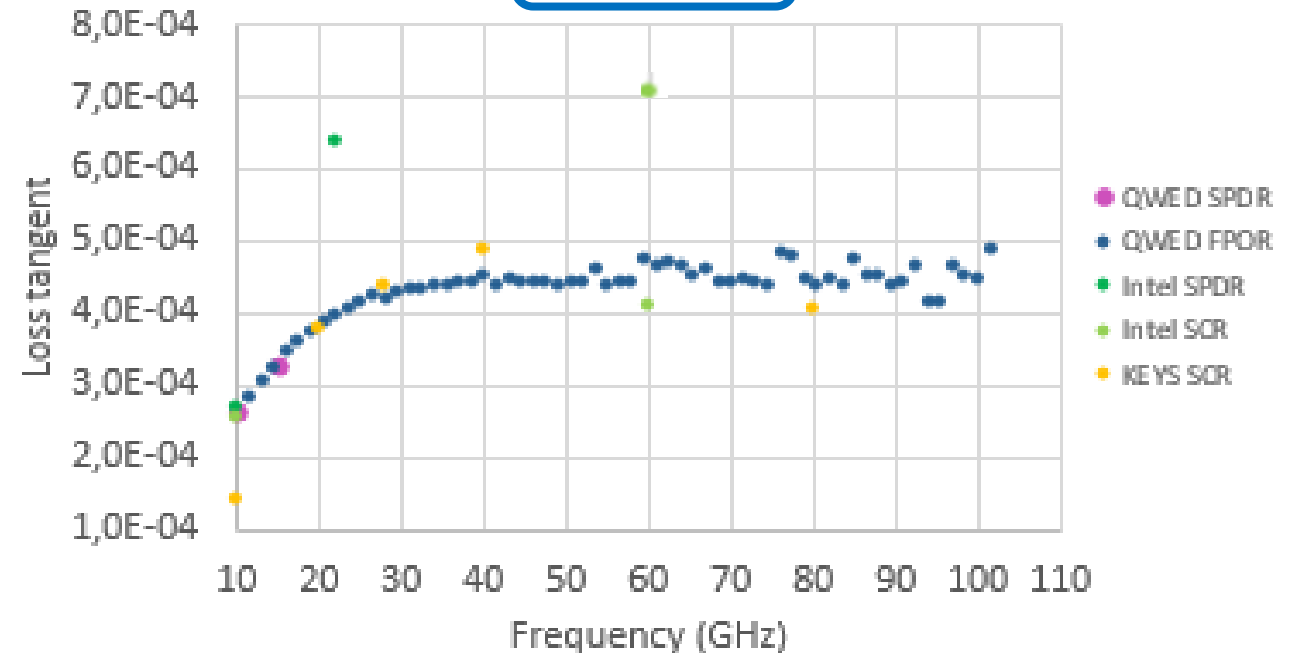
Intel, Keysight – benchtop VNA with Keysight Option N1500A
 QWED FPOR – benchtop VNA with customised FPOR software
 QWED SPDR – handheld VNA , extraction based on abs(S21)

COP 186µm



dot colours denote testing sites

COP 186µm

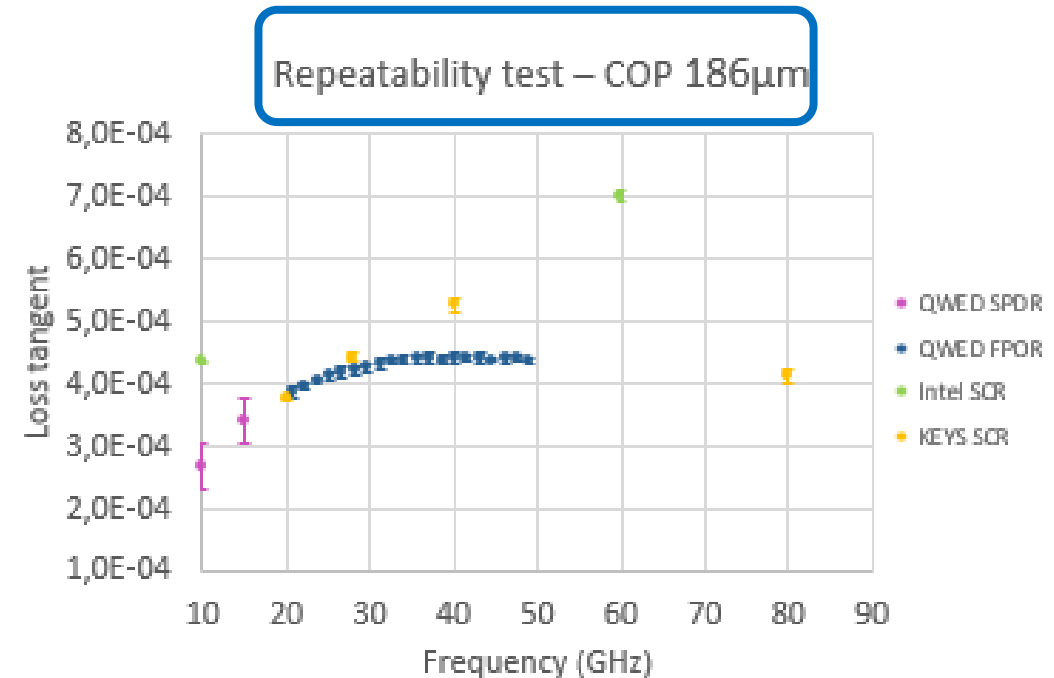
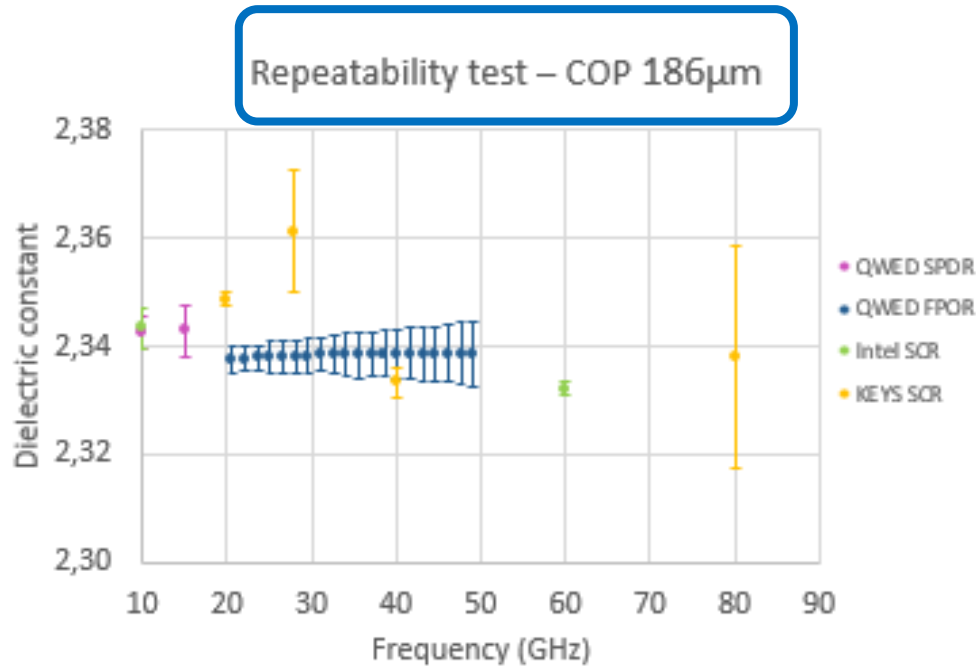


Dk spread < 1% (within $\pm 0.5\%$ from average)
 (< 2% incl. outliers)

> 40GHz 2x increase in Df compared to 10GHz

3 labs, 3 techniques, 14 laboratory setups
1 operator per setup

Intel - SCR at 10 / 60 GHz and SPDR at 10/ 20 GHz,
Keysight - SCR at 10 / 20 / 28 / 40 / 80 GHz
QWED - SPDR at 10/ 15 GHz and FPOR over 10-110GHz.



repeatability of SCR $\pm 1\%$

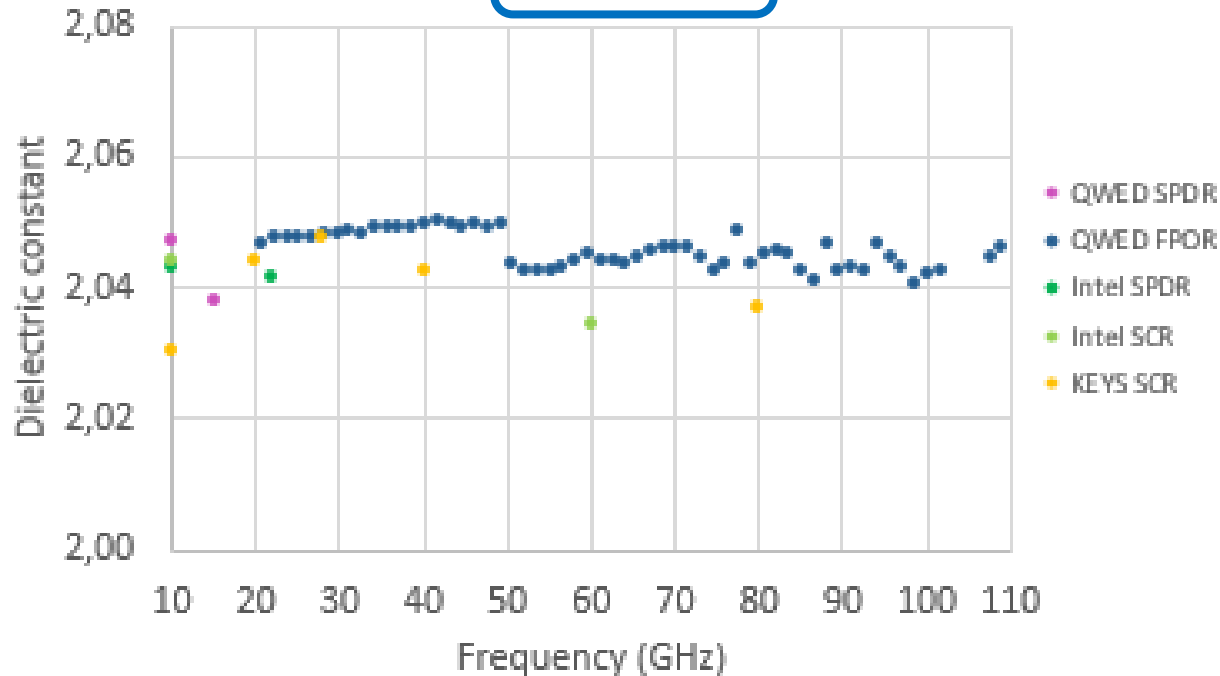
repeatability of SPDR, FPOR better than $\pm 0.5\%$

each symbol denotes an average of 16 measurements; error bar = repeatability = triple of standard deviation

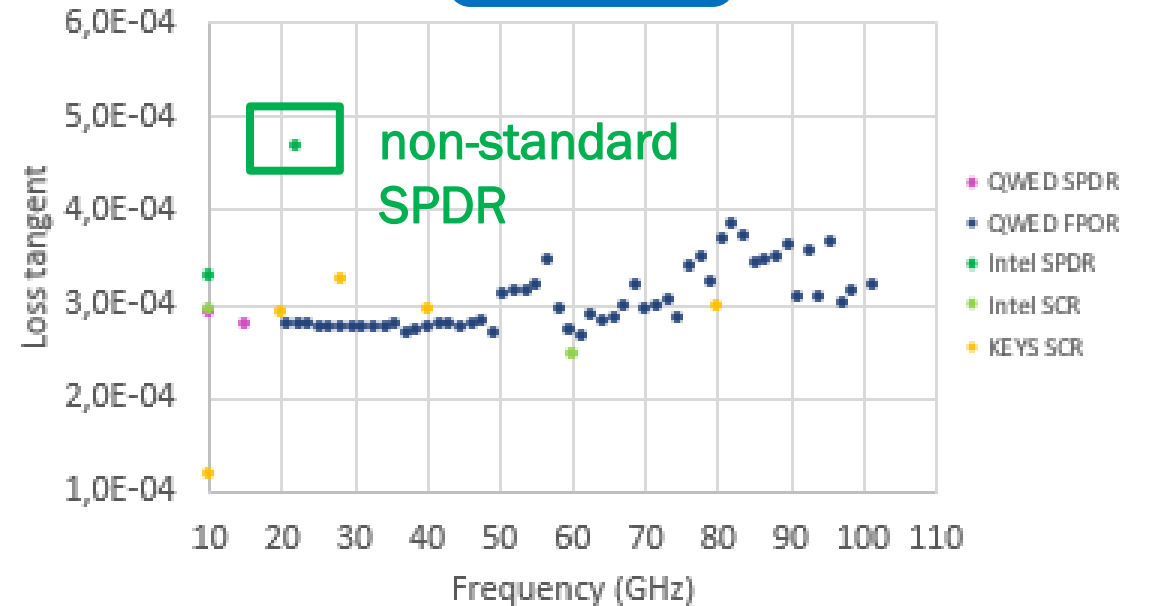
3 labs, 3 techniques, 14 laboratory setups

Intel - SCR at 10 / 60 GHz and SPDR at 10/ 20 GHz,
Keysight - SCR at 10 / 20 / 28 / 40 / 80 GHz
QWED - SPDR at 10/ 15 GHz and FPOR over 10-110GHz.

Teflon 5mils

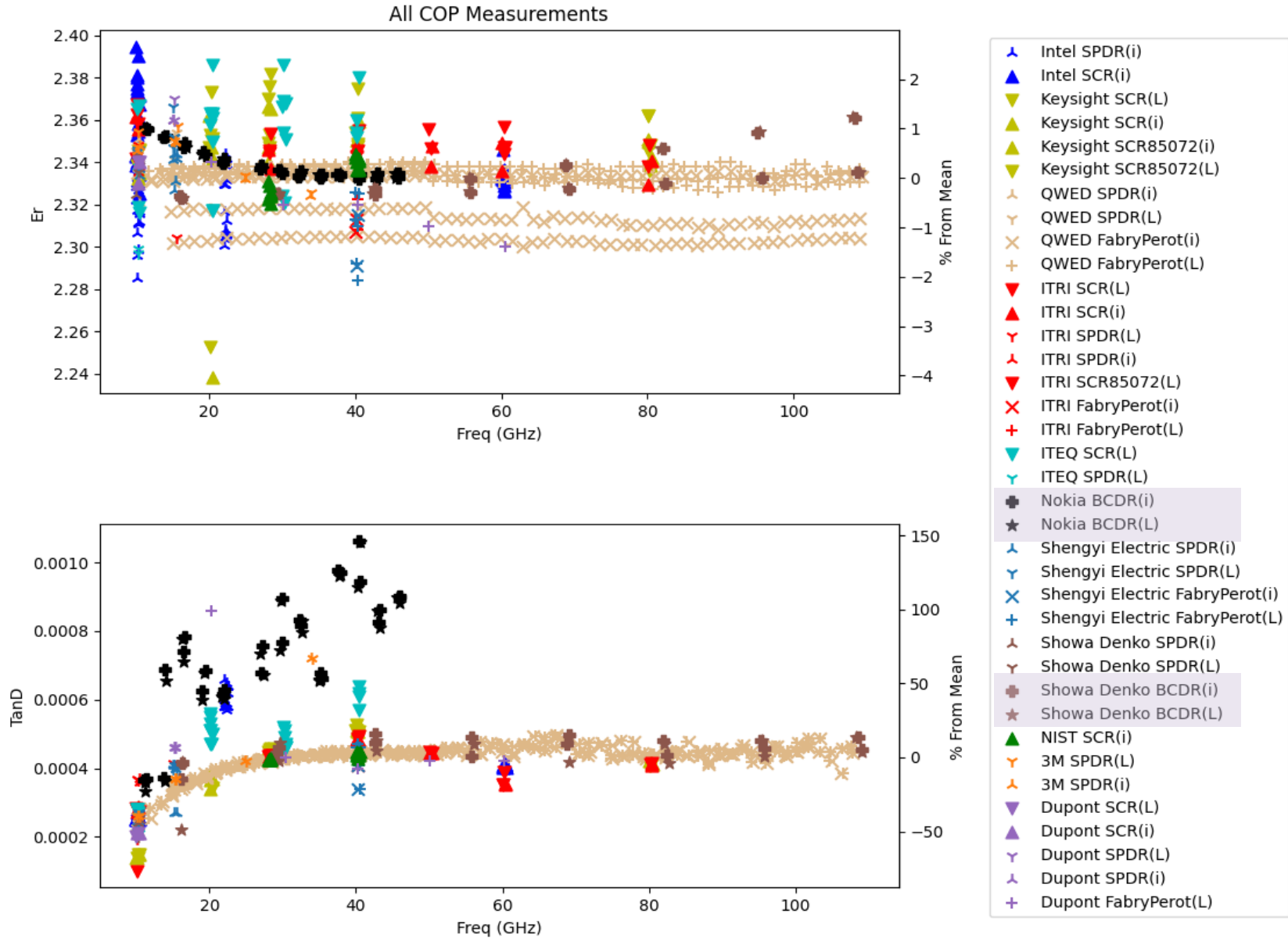


Telfon 5mils

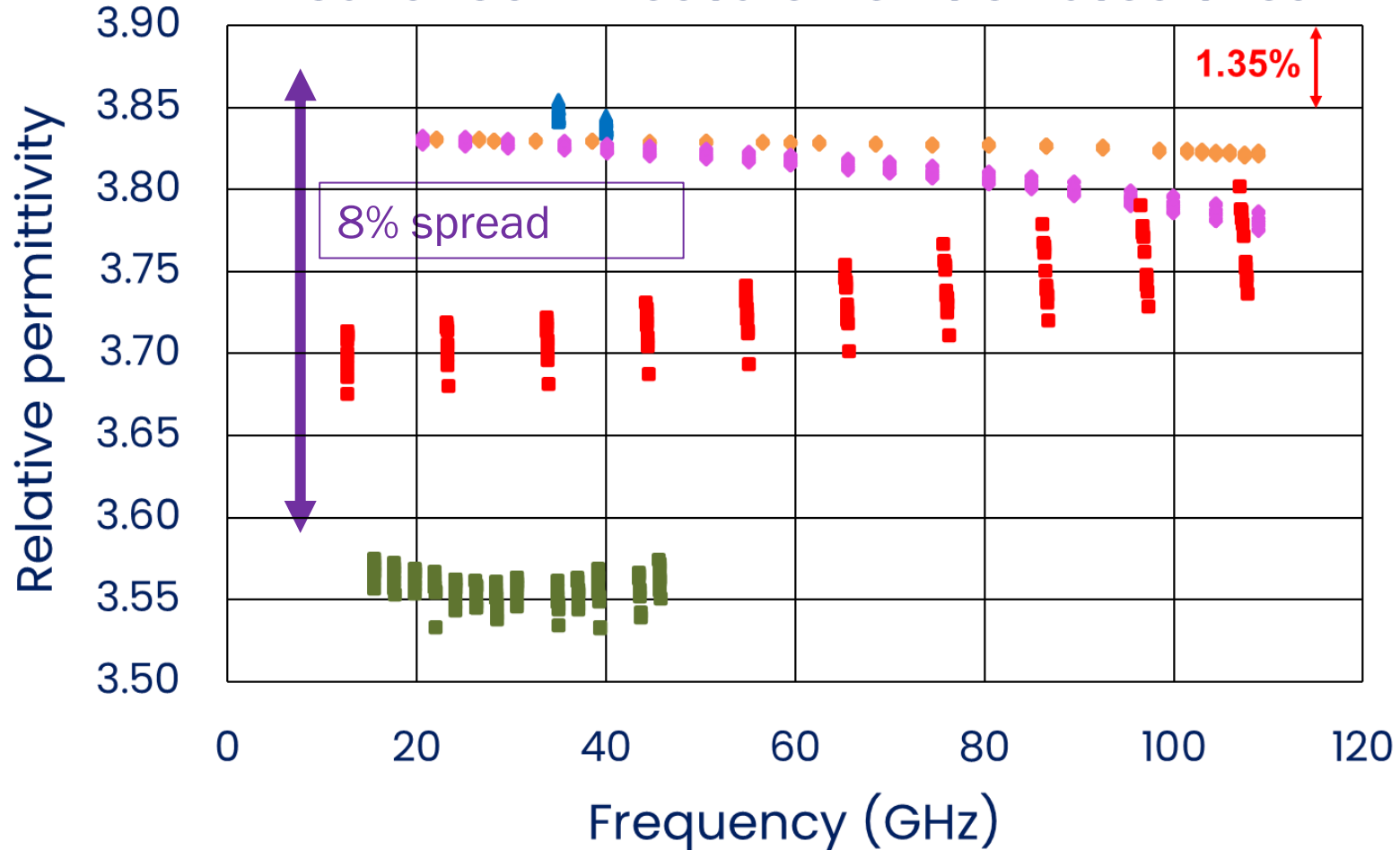


Dk spread < 1% (within $\pm 0.5\%$ from average)

First Round-Robin: All Measurements for COP186 μm



Round robin measurements of fused silica



- ▲ NIST SCR in-plane
- ◆ Lab A FPOR in-plane
- Lab B BCDR out-of-plane
- ◆ Lab C FPOR in-plane
- Lab D BCDR out-of-plane

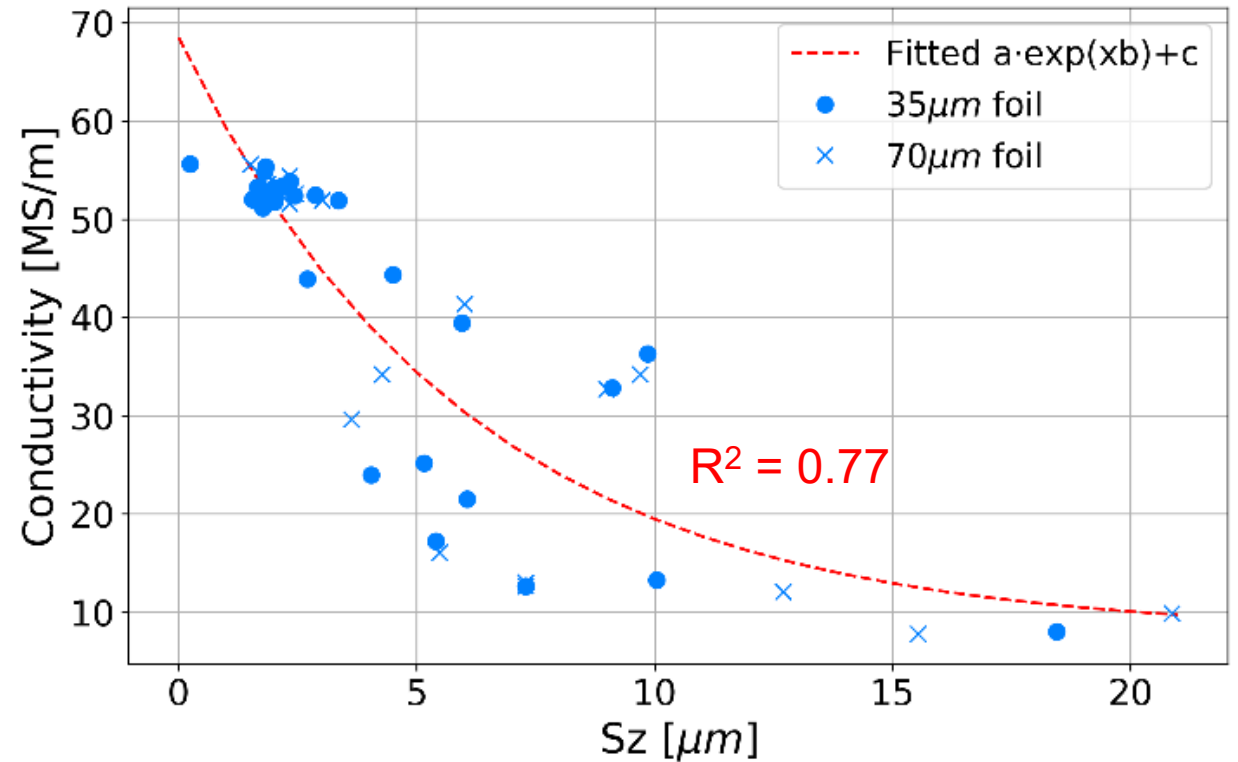
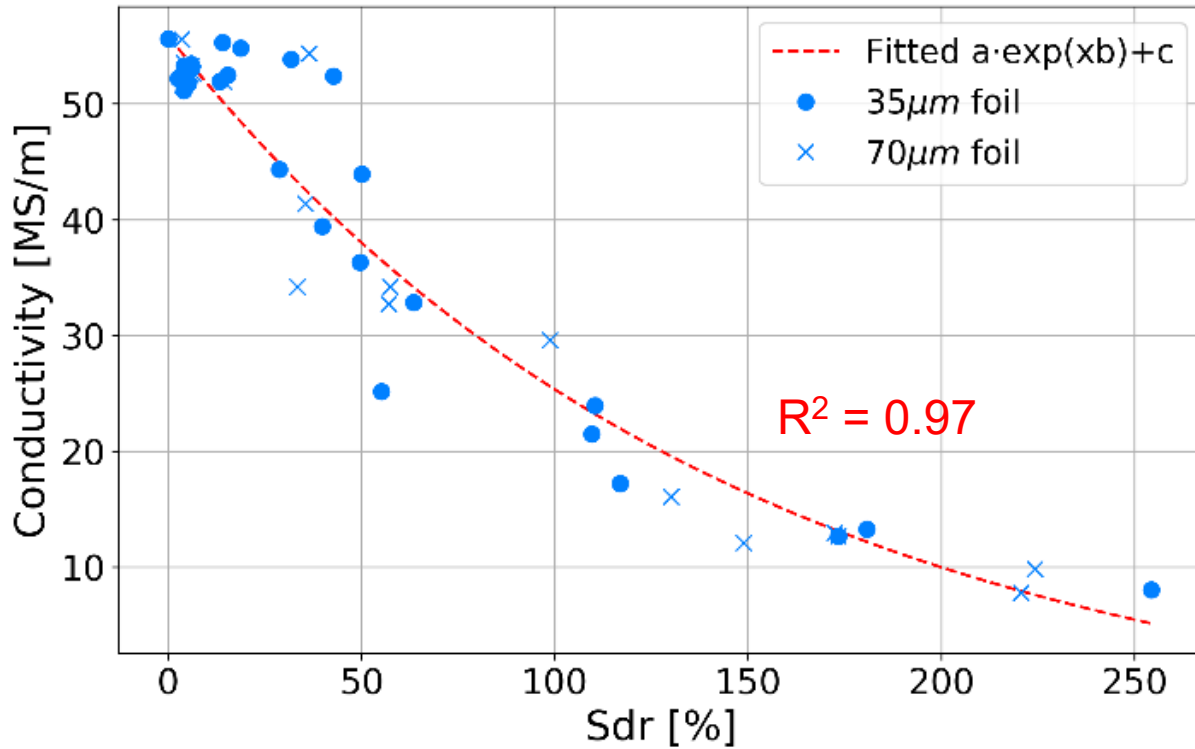
Considered causes of BCDR divergence:

- material anisotropy,
- error inherent in out-of-plane measurement,
- error in particular BCDR instrument.

Testing of Copper Foils for 5G

Correlating effective conductivity to different surface roughness parameters

foils of 35 μm and 70 μm thickness, both sides of each foil



correlation with Sdr (averages) is stronger than with Sz (roughness “amplitudes”)
 Sz, Sdr both obtained with noncontact laser interferometry
 correlation is weaker with Rz, Ra obtained with stylus profilometer

Conclusions



1. Materials are enablers for many industrial technologies
 - novel materials are needed as well as accurate materials' data.
2. At higher MW frequencies, due to the lack of standardized testing techniques and SRMs,
 - the gap must be filled by coordinated benchmarking activities.
3. QWED contributes to such activities thanks to its combination
 - of computer modeling and material measurement competencies.
4. Will MTT-S coordinate future benchmarking and standardization activities for FutureG materials?...

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